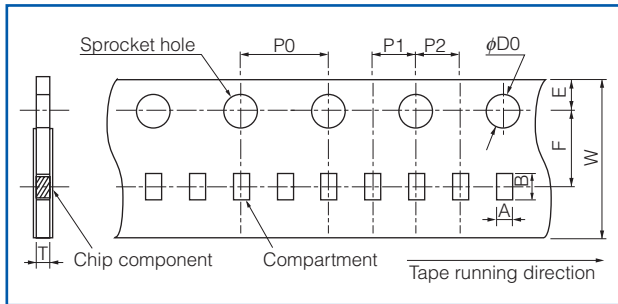


Packaging Methods (Taping)

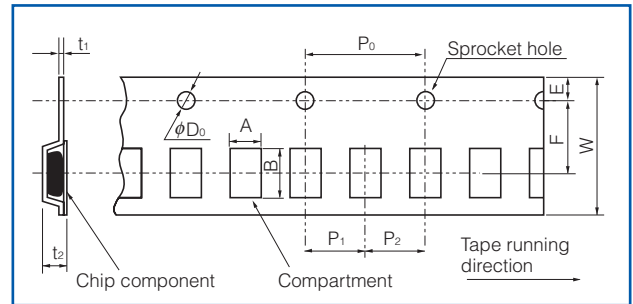
- Standard Quantity

| Part Number | Size (inch) | Type | Kind of Taping | Pitch (P ₁) | Quantity |
|-------------|-------------|--------|-------------------------|-------------------------|------------------|
| EXCX4C | 0202 | Single | Pressed Carrier Taping | 2 mm | 10,000 pcs./reel |
| EXC14C | 0302 | | | | |
| EXC16C | 0403 | | Embossed Carrier Taping | 4 mm | 5,000 pcs./reel |
| EXC24C | 0504 | | | | |
| EXC34C | 0805 | | | | |
| EXC18C | 0603 | Array | Embossed Carrier Taping | 4 mm | 5,000 pcs./reel |
| EXC28C | 0804 | | | | |

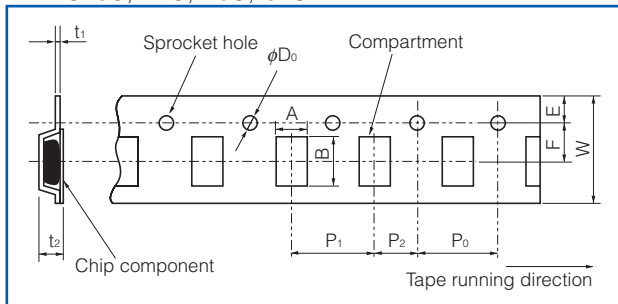
- Pressed Carrier Taping
EXCX4C



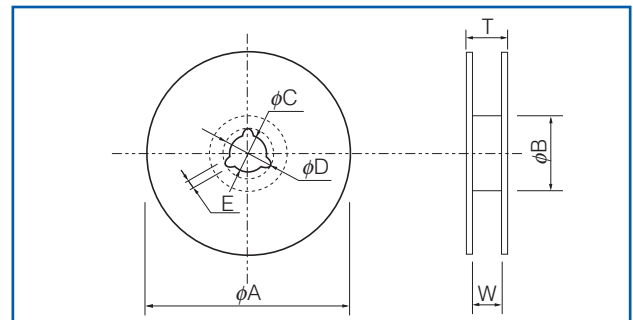
- Embossed Carrier Taping
EXC14C, 16C



- Embossed Carrier Taping
EXC18C, 24C, 28C, 34C



- Taping Reel



- Pressed Carrier Taping

(mm)

| Part Number | A | B | W | F | E | P ₁ | P ₂ | P ₀ | φD ₀ | T |
|-------------|-----------|-----------|---------|-----------|-----------|----------------|----------------|----------------|----------------------------------|-----------|
| EXCX4C | 0.60±0.10 | 0.80±0.10 | 8.0±0.2 | 3.50±0.05 | 1.75±0.10 | 2.0±0.1 | 2.0±0.1 | 4.0±0.1 | 1.5 ^{+0.1} ₀ | 0.35 typ. |

- Embossed Carrier Taping

(mm)

| Part Number | A | B | W | F | E | P ₁ | P ₂ | P ₀ | φD ₀ | t ₁ | t ₂ |
|-------------|-----------|-----------|---------|-----------|-----------|----------------|----------------|----------------|----------------------------------|----------------|----------------|
| EXC14C | 0.75±0.10 | 0.95±0.10 | 8.0±0.2 | 3.50±0.05 | 1.75±0.10 | 2.0±0.1 | 2.0±0.1 | 4.0±0.1 | 1.5 ^{+0.1} ₀ | 0.25±0.05 | 0.85±0.15 |
| EXC16C | 0.77±0.10 | 0.99±0.10 | | | | | | | | | 0.80±0.15 |
| EXC18C | 1.00±0.10 | 1.80±0.10 | 8.0±0.2 | 3.5±0.1 | 1.75±0.10 | 4.0±0.1 | 2.0±0.1 | 4.0±0.1 | 1.5 ^{+0.1} ₀ | 0.25±0.05 | 0.80±0.05 |
| EXC24C | 1.20±0.15 | 1.45±0.15 | | | | | | | | | 0.90±0.15 |
| EXC28C | 1.20±0.15 | 2.25±0.15 | | | | | | | | | |
| EXC34C | 1.50±0.20 | 2.30±0.20 | | | | | | | | | |

- Taping Reel

Standard Reel Dimensions

(mm)

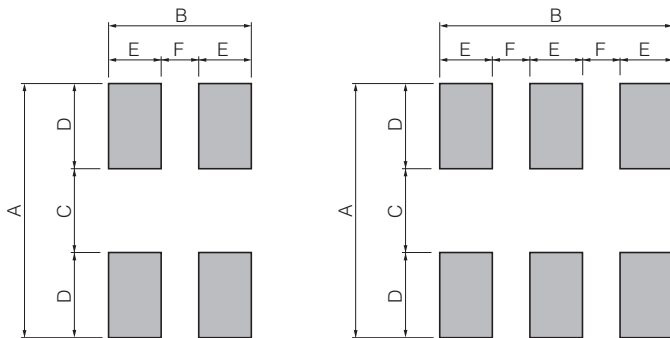
| Part Number | φA | φB | φC | φD | E | W | T |
|-------------|-----------|----------|----------|----------|---------|---------|----------|
| EXCX4C | 180.0±3.0 | 60.0±1.0 | 13.0±0.2 | 21.0±0.8 | 2.0±0.5 | 9.0±0.3 | 11.4±1.0 |
| EXC14C | | | 13.0±0.5 | | | | 11.4±1.5 |
| EXC16C | | | | | | | |
| EXC18C | | | | | | | |
| EXC24C | | | | | | | |
| EXC28C | | | | | | | |
| EXC34C | | | | | | | |

Recommended Land Pattern Design

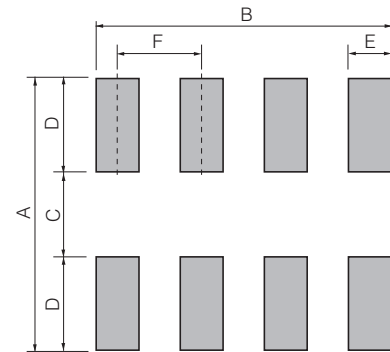
● Single

EXCX4C, 14C, 24C, 34C

EXC16C



● Array



| Part Number | Dimensions (mm) | | | | | |
|-------------|-----------------|--------------|--------------|--------------|--------------|--------------|
| | A | B | C | D | E | F |
| EXCX4C | 0.80 to 0.90 | 0.60 to 0.75 | 0.20 to 0.30 | 0.30 | 0.20 to 0.25 | 0.20 to 0.25 |
| EXC14C | 0.80 to 1.00 | 0.80 | 0.30 | 0.25 to 0.35 | 0.30 | 0.20 |
| EXC24C | 1.60 to 2.00 | 0.95 | 0.70 | 0.45 to 0.65 | 0.35 | 0.25 |
| EXC34C | 2.60 | 1.20 | 1.10 | 0.75 | 0.40 | 0.40 |
| EXC16C | 0.99 | 0.85 | 0.33 | 0.33 | 0.15 | 0.20 |

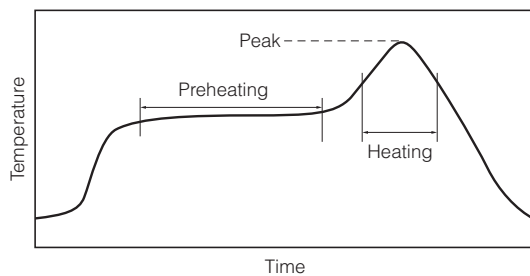
| Part Number | Dimensions (mm) | | | | | |
|-------------|-----------------|------|-----|-----|------|-----|
| | A | B | C | D | E | F |
| EXC18C | 1.4 | 1.4 | 0.4 | 0.5 | 0.2 | 0.4 |
| EXC28C | 1.4 | 1.75 | 0.4 | 0.5 | 0.25 | 0.5 |

Recommended Soldering Conditions

Recommendations and precautions are described below

● Recommended soldering conditions for reflow

- Reflow soldering shall be performed a maximum of two times.
- Please contact us for additional information when used in conditions other than those specified.
- Please measure the temperature of the terminals and study every kind of solder and printed circuit board for solderability before actual use.



● Flow soldering

- We do not recommend flow soldering, because flow soldering may cause bridges between the electrodes.

For soldering (Example : Sn-37Pb)

| | Temperature | Time |
|--------------|------------------|---------------|
| Preheating | 140 °C to 160 °C | 60 s to 120 s |
| Main heating | Above 200 °C | 30 s to 40 s |
| Peak | 235 ± 10 °C | max. 10 s |

For lead-free soldering (Example : Sn/3Ag/0.5Cu)

| | Temperature | Time |
|--------------|------------------|---------------|
| Preheating | 150 °C to 170 °C | 60 s to 120 s |
| Main heating | Above 230 °C | 30 s to 40 s |
| Peak | max. 260 °C | max. 10 s |

<Repair with hand soldering>

- Preheat with a blast of hot air or similar method. Use a soldering iron with a tip temperature of 350 °C or less. Solder each electrode for 3 seconds or less.
- Never touch this product with the tip of a soldering iron.